

### IN THE CLAIMS

Please amend the claims as described herein below.

1. A method for forming a package device, comprising:
  - providing a package substrate having a first surface along a first plane and second surface along a second plane, wherein the package substrate has a cavity between the first plane and the second plane;
  - attaching a tape to the package substrate along the first plane;
  - placing a first integrated circuit on the tape and in the cavity;
  - depositing encapsulating material over the first integrated circuit;
  - removing the tape;
  - placing a second integrated circuit adjacent to the first integrated circuit outside the cavity; and
  - depositing encapsulating material over the second integrated circuit.
2. The method of claim 1, wherein the package substrate further comprises first pads on the first surface and second pads on the second surface and first bond fingers on the first surface and second bond fingers on the second surface, further comprising:
  - electrically connecting the first integrated circuit to the first pads;
  - electrically connecting the second integrated circuit to the second pads; and
  - testing the first integrated circuit and the second integrated circuit by applying test probes to the first pads and the second pads.

A1

3(Once Amended). A method of forming a package device, comprising:

- providing a package substrate having a first side and a second side and having first pads on the first side and second pads on the second side;
- placing a first integrated circuit on the first side and a second integrated circuit on a second side, wherein no substrate is interposed between the first integrated circuit and the second integrated circuit;
- electrically connecting the first integrated circuit to the first pads and the second integrated circuit to the second pads; and
- testing the first integrated circuit and the second integrated circuit by applying test probes to the first pads and the second pads,

wherein at least one of the first pads is electrically independent of all of the second pads.

4. The method of claim 3, wherein the step of attaching is further characterized by: the first integrated circuit being placed on the first side prior to the second integrated circuit being placed on the second side.

5. The method of claim 4, wherein the step of electrically connecting is further characterized by:

- the first integrated circuit being electrically connected to the first pads prior to the second integrated circuit being electrically connected to the second pads.

A2

6(Once Amended). A method for forming a package device, comprising:

- providing a package substrate having a first surface along a first plane and second surface along a second plane, wherein the package substrate has a cavity between the first plane and the second plane;

A2  
placing a first integrated circuit in the cavity;  
placing a second integrated circuit adjacent to the first integrated circuit  
outside the cavity, such that no substrate is interposed between the first  
integrated circuit and the second integrated circuit; and  
depositing encapsulating material over the first integrated circuit and the  
second integrated circuit.

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7. The method of claim 6, wherein the step of depositing comprises:  
depositing a first portion of the encapsulating material over the first integrated  
circuit prior to the step of placing the second integrated circuit; and  
depositing a second portion of the encapsulating material over the second  
integrated circuit.
8. The method of claim 7, further comprising:  
placing a third integrated circuit adjacent to the second integrated circuit prior  
to the step of depositing the second portion of encapsulating material.
9. The method of claim 6, wherein the package substrate further comprises first  
pads on the first surface, second pads on the second surface, first bond fingers on  
the first surface, and second bond fingers on the second surface, further  
comprising;  
electrically connecting the first integrated circuit to the first pads;  
electrically connecting the second integrated circuit to the second pads; and  
testing the first integrated circuit and the second integrated circuit by applying  
test probes to the first pads and the second pads.

10. The method of claim 9, wherein the step of electrically connecting the first integrated circuit comprises wire bonding.

11. The method of claim 6, wherein the package substrate further comprises a supporting member along the second plane of the substrate.

12. The method of claim 11, wherein the supporting member is between the first integrated circuit and the second integrated circuit.

13. The method of claim 12, wherein the supporting member is electrically conductive.

14. The method of claim 11, further comprising removing the supporting member prior to step of placing the second integrated circuit.

15. The method of claim 14, wherein supporting member is tape.

28(New). The method of claim 7, wherein the step of depositing the first portion of the encapsulating material comprises transfer molding the encapsulating material, and wherein the step of depositing a second portion of the encapsulating material comprises transfer molding the encapsulating material.

29(New). The method of claim 8, wherein the third integrated circuit is stacked at least partially overlying at least one of the first and second integrated circuits.